

| PCN Number: | 20141121003 | | | PCN Date: | 12/04/2014 | | | | | | |
|---|---|---------------------------------------|---------------------------|-------------------------------------|--------------------------|------|---------|-----|---------------|------------------------------|---------------|
| Title: | Qualification of New Mold Compound for selected Devices in the PDIP package | | | | | | | | | | |
| Customer Contact: | PCN Manager | Phone: | +1(214)480-6037 | Dept: | Quality Services | | | | | | |
| Proposed 1st Ship Date: | 3/04/2015 | Estimated Sample Availability: | | Date provided upon request | | | | | | | |
| Change Type: | | | | | | | | | | | |
| <input type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | Assembly Materials | | | | | | |
| <input type="checkbox"/> | Design | <input type="checkbox"/> | Electrical Specification | <input type="checkbox"/> | Mechanical Specification | | | | | | |
| <input type="checkbox"/> | Test Site | <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process | | | | | | |
| <input type="checkbox"/> | Wafer Bump Site | <input type="checkbox"/> | Wafer Bump Material | <input type="checkbox"/> | Wafer Bump Process | | | | | | |
| <input type="checkbox"/> | Wafer Fab Site | <input type="checkbox"/> | Wafer Fab Materials | <input type="checkbox"/> | Wafer Fab Process | | | | | | |
| | <input type="checkbox"/> | | Part number change | | | | | | | | |
| PCN Details | | | | | | | | | | | |
| Description of Change: | | | | | | | | | | | |
| Texas Instruments is pleased to announce the qualification of a new mold compound for the list of selected PDIP packaged devices shown below. | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>What</th> <th>Current</th> <th>New</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SID#101331374 or SID#8000779</td> <td>SID#101375725</td> </tr> </tbody> </table> | | | | | | What | Current | New | Mold Compound | SID#101331374 or SID#8000779 | SID#101375725 |
| What | Current | New | | | | | | | | | |
| Mold Compound | SID#101331374 or SID#8000779 | SID#101375725 | | | | | | | | | |
| Reason for Change: | | | | | | | | | | | |
| Material Standardization | | | | | | | | | | | |
| Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): | | | | | | | | | | | |
| None | | | | | | | | | | | |

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| Changes to product identification resulting from this PCN: |
| None |

| Product Affected | | | |
|-------------------------|------------------|------------------|-----------------|
| ADC0831CCN | LF412ACN | LM2904N/NOPB | LM4562NA/NOPB |
| ADC0832CCN | LF412CN | LM2904N/SL161612 | LM6134BIN |
| COP431CN | LF442CN/NOPB | LM2907N-8/NOPB | LM6134BIN/NOPB |
| COP432CN | LF444CN/NOPB | LM2917N-8/NOPB | LM78S40N |
| DAC0808LCN/SL107322 | LM10CN/NOPB | LM2917N/NOPB | LM833N/NOPB |
| DS14C88N/NOPB | LM13700N | LM311N | LMC6042AIN |
| DS26LS32ACN | LM231N/NOPB | LM311N/NOPB | LMC6042IN/NOPB |
| DS26LS32ACN/NOPB | LM2574N-12 | LM319N | LMC6044IN |
| DS3668N | LM2574N-ADJ | LM324AN/NOPB | LMC6044IN/NOPB |
| DS3668N/HAPB | LM2594N-12/NOPB | LM324AN/PB | LMC6064IN |
| DS3695N | LM2594N-3.3/NOPB | LM324N/NOPB | LMC6462AIN |
| DS3695TN | LM2597N-5.0/NOPB | LM339N/NOPB | LMC6462AIN/NOPB |
| DS75176BN | LM2671N-5.0 | LM348N/NOPB | LMC6464BIN |
| DS8921N/NOPB | LM2671N-ADJ/NOPB | LM3524DN | LMC6482AIN |

| | | | |
|---------------|------------------|---------------|-----------------|
| DS8923AN | LM2672N-12/NOPB | LM3524DN/NOPB | LMC6482AIN/NOPB |
| DS8923AN/NOPB | LM2672N-ADJ/NOPB | LM358N | LMC6484AIN/NOPB |
| DS96175CN | LM2674N-12/NOPB | LM358N/NOPB | LMC660CN |
| DS96176CN | LM2674N-5.0/NOPB | LM361N/NOPB | LMC7660IN/NOPB |
| LF353N | LM2675N-12/NOPB | LM386N-1/NOPB | LME49720NA/NOPB |
| LF356N/NOPB | LM2675N-5.0/NOPB | LM386N-3 | LME49860NA/NOPB |
| LF398N | LM2901N/NOPB | LM386N-3/NOPB | MLM311P |
| LF398N/NOPB | LM2901N/SL65262 | LM386N-4/NOPB | TL072 |
| LF411ACN/NOPB | LM2903N/NOPB | LM393N/NOPB | TP3054N |
| LF411CN/NOPB | | | |

Qualification Report

PDIP mold compound SID#8000779 discontinuance in AP1 Approved 06/10/2014

Product Attributes

| Attributes | Qual Device: LF444CN/NOPB | Qual Device: LM319N |
|--------------------|---------------------------|---------------------|
| Assembly Site | AP1 | AP1 |
| Package Family | PDIP | PDIP |
| Wafer Fab Supplier | GL | GL |
| Wafer Fab Process | BPBIFET.13.1 | BPSLM.8.1 |

- QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | Test Name / Condition | Duration | Qual Device: LF444CN/NOPB | Qual Device: LM319N |
|-------|--|------------|---------------------------|---------------------|
| THB | Biased Temperature and Humidity, 85C/85%RH | 1000 Hours | - | 3/140/0 |
| AC | Autoclave 121C | 96 Hours | 3/240/0 | - |
| UHAST | Unbiased HAST 130C/85%RH | 96 Hours | 3/240/0 | - |
| TC | Temperature Cycle, -65/150C | 500 Cycles | - | 3/240/0 |
| HTSL | High Temp Storage Bake 150C | 1000 Hours | 3/240/0 | - |

-- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20130502-84221

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|-----------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |